

### PCB SMD NUT CONNECTOR

电路板表贴螺母柱连接器

下列条件适用于 SMD 产品系列内的所有零件:

- •请参照技术手册中的建议设计电路板。
- •必须根据回流焊/波峰焊技术规范选择合格的焊料,严格控制焊接温度、时间。 •焊接工艺会导致产品表面变色。
- •爬锡现象会导致内孔堵塞,因此通孔产品不适用波峰焊,建议采用回流焊。 •所有产品应在出厂 12 个月内使用,超出有效期会影响可焊性。
- •必须在密封、干燥环境下保存。
- ·零件与 PCB 的连接强度由产品、焊盘、焊接效果等因素综合决定
- ·必须控制最大锁附扭力,防止元件和 PCB 受到机械破坏。
- •工作电流由PCB、电缆接头、电缆横截面等因素综合决定。
- •手册中如有标注参考电流,零件使用材料为黄铜 C3604(H59)

### **Cautions and Warnings:**

The following conditions apply to all goods within the product series of viyuan PCB SMD

#### General:

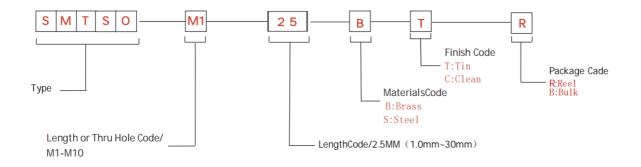
All recommendations according to the general technical specifications of the data-sheet have to be complied with.

The responsibility for the applicability of customer specific products and use in a particular customer design is always within the authority of the customer. All technical specifications for standard products do also apply for customer specific products.

### Product Specific:

Follow all instructions in the datasheet, especially:

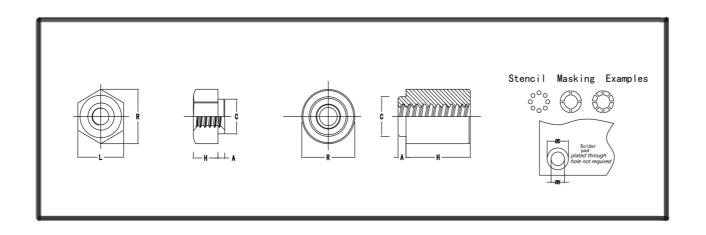
- •The solder profile has to be complied with according to the technical reflow soldering specification, otherwise no warranty will be sustained.
- •Surface discoloration due to reflow processing is permitted.
- Wave soldering is not applicable. Reflow soldering is recommended.
- •All products shall be used before the end of the period of 12 months based on the product date-code, if not a 100% solderability can't be ensured.
- •The maximum permissible torques must be complied with to prevent mechanical destruction of the elements and PCB.
- Operating current depends on PCB, cable lug and cross section of the cableo
- •The connection strength between parts and PCB is determined by product, pad and welding effect
- •If the operating current is marked in the manual, the material used for the parts is brass C3604(H59)





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Thread sizes 080, S1, S1.2, S1.4 and M1.6

Therad/thru hole sizes M2, M2, M2, 5, M3, M3. 5, M4, 3. 6, 4. 2

11	dimensions	are	in	milineters

	Thread Size x Pitch	Thru Hole +0.10 -0.08	Туре	1hread or Thru Hole Code				Leng	gth Co	ode"	H"±(	).13	(Len	gth	code	in m	illim	eters	s)			Bel	ow is	engt	hole v h Co Lengtl	de"I	I''±0. e in		depth	Min. Sheet Thickne	Max.	A ( Max.	Ref	±0.13	L Nom	Hole Size In Sheet +0.08	<b>0D</b> Min.Solder Pad	Rated Current (A)	Tightening Torque (Kgf.cm)
	M 1x0.25	_	SMTSO	M1	0.5	1	1.5	2	2.5	3	-	_	_	_	-			_	-	_	_	_	_	_	_				_	0.5	0.48	2.41	3.66	_	3.18	2.5	4.19	15	0.3
	M1.2x0.25	_	SMTSO	M1.2	0.5	1	1.5	2	2.5	3										_										0.5	0.48	2.41	3.66	_	3.18	2.5	4.19	15	0.6
3	M1.4x0.3	_	SMTSO	M1.4	0.5	1	1.5	2	2.5	3										_										0.5	0.48	2.41	3.66	-	3.18	2.5	4.19	15	1
METRIC	M1.6x0.35	_	SMTSO	M1.6	0.5	1	1.5	2	2.5	3	_		_			-		_	_		_		_		_	_	_	_	_	0.5	0.48	2.41	3.66	_	3.18	2.5	4.19	15	1.5
	M2x0.4	_	SMTSO	M2	0.5	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	3.6	-	5.56	_	3.73	6.2	30	1.5
公制尺寸	M2.5x0.45	_	SMTSO	M2.5	_	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	4.09	_	5.56	_	4.22	6.2	30	3
4	M3x0.5	_	SMTSO	M3	-	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	4.09	-	5.56	-	4.22	6.2	30	5
	M3.5x0.6	_	SMTSO	M3.5	_	F	_	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	5.28	_	7.14	_	5.41	7.77	40	6
	M4x0.7	_	SMTSO	M4		-		2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	6.22	-	8.74	-	6.35	9.37	50	8
	_	3.2	SMTSO	K	_	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10					_				1.53	1.53	4.09	-	5.56	_	4.22	6.2	20	_
	_	3.6	SMTSO	L	<u> </u>	-	-	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10					_				1.53	1.53	5.28	-	7.14	-	5.41	7.77	30	_
	_	4.2	SMTSO	M		L		2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10									1.53	1.53	6.22		8.74		6.35	9.37	40	_

[多"L"尺寸未列在表中,请略我们确认! MORE "L" SIZES ARE NOT LISTED IN THE TABLE, PLEASE CONTACT US FOR

Thread s i zes 0, S1, S1.2, S1.4 and M1.6

Therad/thru hole sizes M2, M. 5, M3, M3. 5, M4, 3. 6, 4. 2

2, 4, 6, 8, 116 and 143

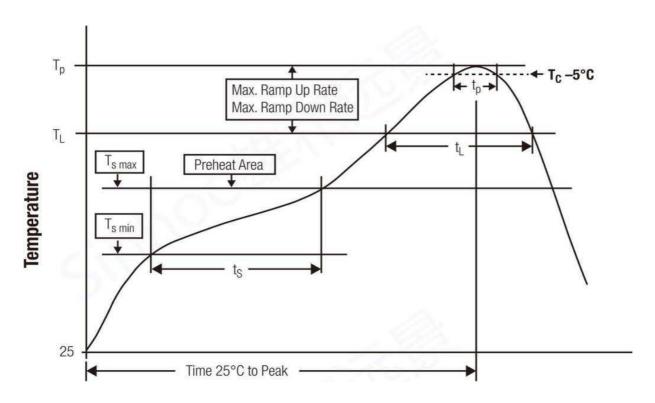
All dimensions are in inches.

	Thread Size	Thru Hole +.004003	Туре	Thread or Thru Hole	Length	ı Code"H'	'±.005 (Lei	ngth code is	n 32nds of	an inch)	Min. Sheet Thickness		C Max.	R		L Nom.	<b>0H</b> Hole Size In	<b>0D</b> Min.Solder	Rated Current	Tightening Torque
	52.0	1.004005		Code								TVIUX.	- Trace	Ref.	±.005	1101111	Sheet +.003000	Pad	(A)	(Kgf.cm)
	,060-80 (#0-80)	_	SMTSO	0	.062	.125	_	_		_	.020	.019	.095	.144	-	.125	.098	.165	15	1.5
UNIFIED	.086-56 (#2-56)	_	SMTSO	2	.062	.125	.187	.250	.312	.375	.060	.060	.142	_	.219	_	.147	.244	30	1.5
D英制	.112-40 (#4-40)	_	SMTSO	4	.062	.125	.187	.250	.312	.375	.060	.060	.161		.219	_	.166	.244	30	5
下	,060-80 (#6-32)	_	SMTSO	6	.062	.125	.187	.250	.312	.375	.060	.060	.208		.281	-	.213	.306	40	6
4	.164-32 (#8-32)	_	SMTSO	8	.062	.125	.187	.250	.312	.375	.060	.060	.245	_	.344	_	.250	.369	50	8
	_	.116	SMTSO	9	.062	.125	.187	.250	.312	.375	.060	.060	.161		.219	_	.166	.244	30	_
	_	.143	SMTSO	10	.062	.125	.187	.250	.312	.375	.060	.060	.208		.281	_	.213	.306	40	_



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## **Classification Reflow Profile for SMT components:**

### **Classification Reflow Soldering Profile:**

Profile Feature		Value
Preheat Temperature Min()	L min	150 °C
Preheat Temperature Max	Ts max	200 °C
Preheat Time t, from T <sub>smi</sub> ,, to T <sub>smax</sub>	ts	60-120 seconds
Ramp-up Rate (T <sub>L</sub> to T <sub>p</sub> )		3 °C/ second max.
Liquidous Temperature	$T_{L}$	217 °C
Time t <sub>L</sub> maintained above T <sub>L</sub>	Ł	60-150 seconds
Peak package body temperature		see table
Time within 5°C of actual peak temperaure	tp	20 - 30 seconds
Ramp-down Rate (T <sub>L</sub> to T <sub>p</sub> )		6 °C/ second max.
Time 25°C to peak temperature		8 minutes max.

### Package Classification Reflow Temperature:

### Time

Properties	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
PB-Free Assembly I Package Thickness < 1.6 mm	260 °C	260 °C	260 °C
PB-Free Assembly I Package Thickness 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
PB-Free Assembly I Package Thickness > 2.5 mm	250 °C	245 °C	245 °C